

HSN278WK

Silicon Epitaxial Schottky Barrier Diode for Detector

REJ03G0611-0100

(Previous: ADE-208-1524)

Rev.1.00 Sep 13, 2005

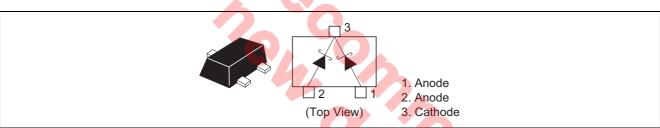
Features

- Low forward voltage, Low capacitance.
- Miniature Flat Lead Package (MFPAK) is suitable for surface mount design.

Ordering Information

Type No.		Laser Mark	Package Name	Package Code (Previous Code)
HSN278WK	•	SI-	MFPAK	PUSF0003ZA-A (MFPAK)

Pin Arrangement



50.70

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

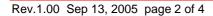
Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Reverse voltage	V_R	30	V
Average rectified current	I ₀	30	mA
Non-Repetitive peak forward surge current	I _{FSM} *	200	mA
Peak forward current	I _{FM}	150	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 10 ms sine wave 1 pulse one device.

Electrical Characteristics

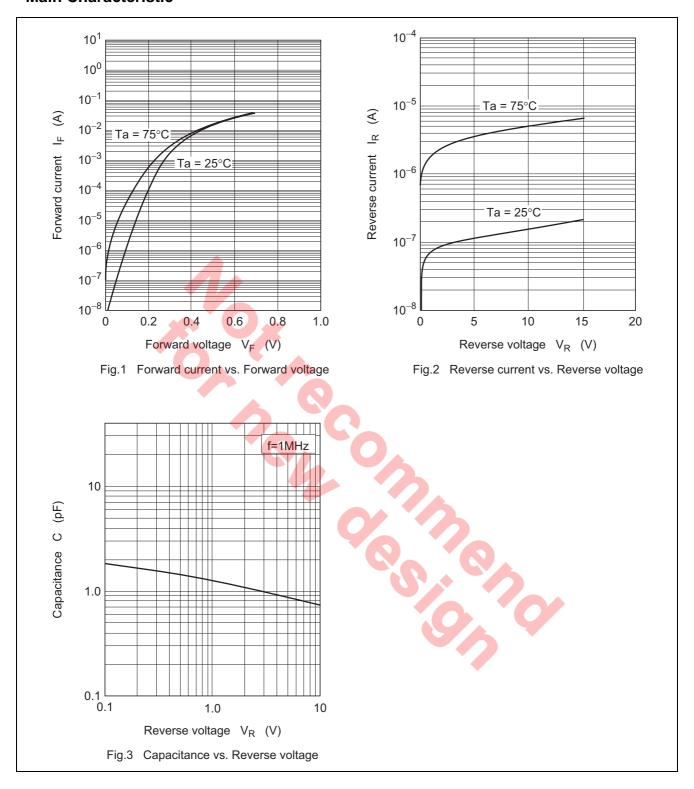
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}		_	0.30	V	I _F = 1 mA
	V _{F2}		· —	0.95		I _F = 30 mA
Reverse current	I_R		_	700	nA	V _R = 10 V
Capacitance	C	_	_	1.5	pF	V _R = 1 V, f = 1 MHz
ESD-Capability *	_	100		_	V	$C = 200 \text{ pF}, R_L = 0 \Omega$, Both forward and reverse direction 1 pulse.
Note: Failure criterion ; $I_R \ge 1.4 \mu A$ at $V_R = 10 \text{ V}$						

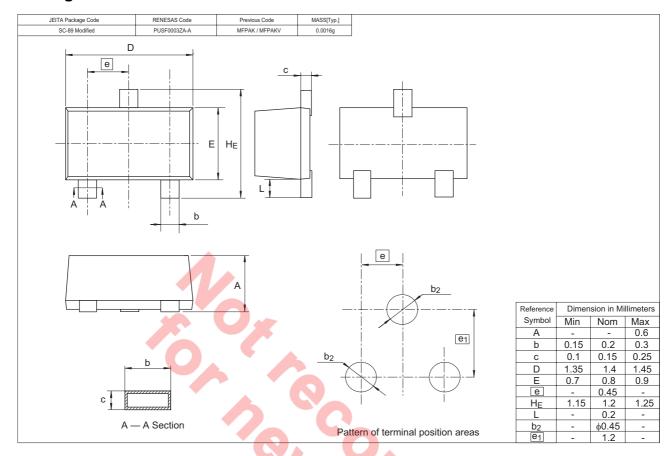




Main Characteristic



Package Dimensions



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